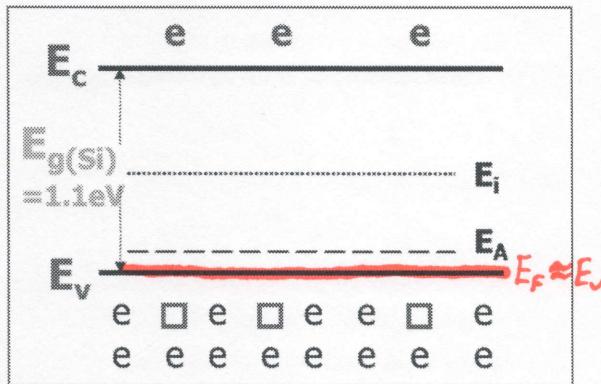


### Problem 1: Energy Bands and Charge Carriers

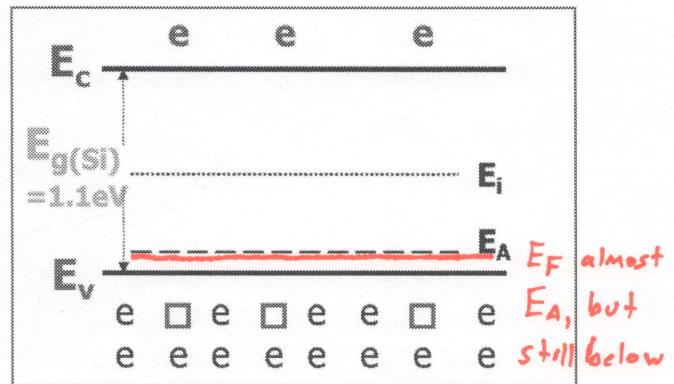
For a p-type Si semiconductor with an acceptor concentration  $N_A = 10^{14} \text{ cm}^{-3}$ , an acceptor level 15 meV away from the valence band edge, and an intrinsic carrier concentration  $n_i(300\text{K}) \sim 1.5 \times 10^{10} \text{ cm}^{-3}$  and  $n_i(500\text{K}) \sim 5 \times 10^{14} \text{ cm}^{-3}$ :

Draw the Fermi level for the 4 different temperature regions a) 0K, b) 50K, c) 300K, and d) 500K:

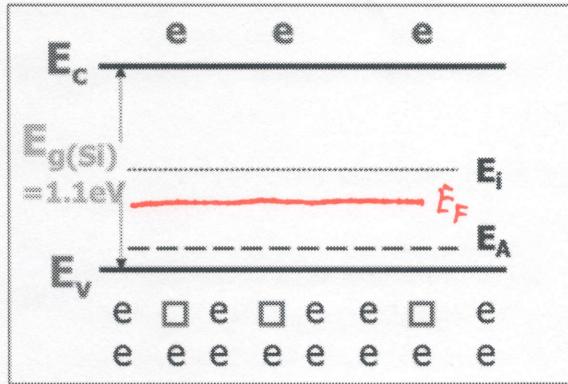
a) Fermi Level @ 0K (5 pts)



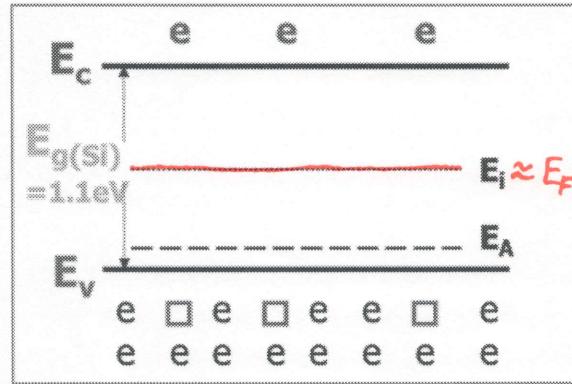
b) Fermi Level @ 50K (5 pts)



c) Fermi Level @ 300K (5 pts)



d) Fermi Level @ 500K (5 pts)



$T = 0\text{K}$ :  $E_F$  represents the top of the "electron sea" meaning that it should be placed at exactly the uppermost filled electron state, which is  $E_v$ .

$T = 50\text{K}$ : The temperature is still very low, though it is finite so some of the acceptors have ionized, meaning electrons now exist at  $E_A$  and holes in  $E_v$ . Since the Fermi function changes very rapidly around  $E_F$ , we know it must be close to  $E_A$ . It cannot be above  $E_A$  since that would imply a significant number of acceptors are ionized, which is not the case.

$T = 300\text{K}$ : All acceptors ionized and  $p_0 \gg n_i$  so  $E_F$  is in the middle (or close to)  $E_i - E_v$

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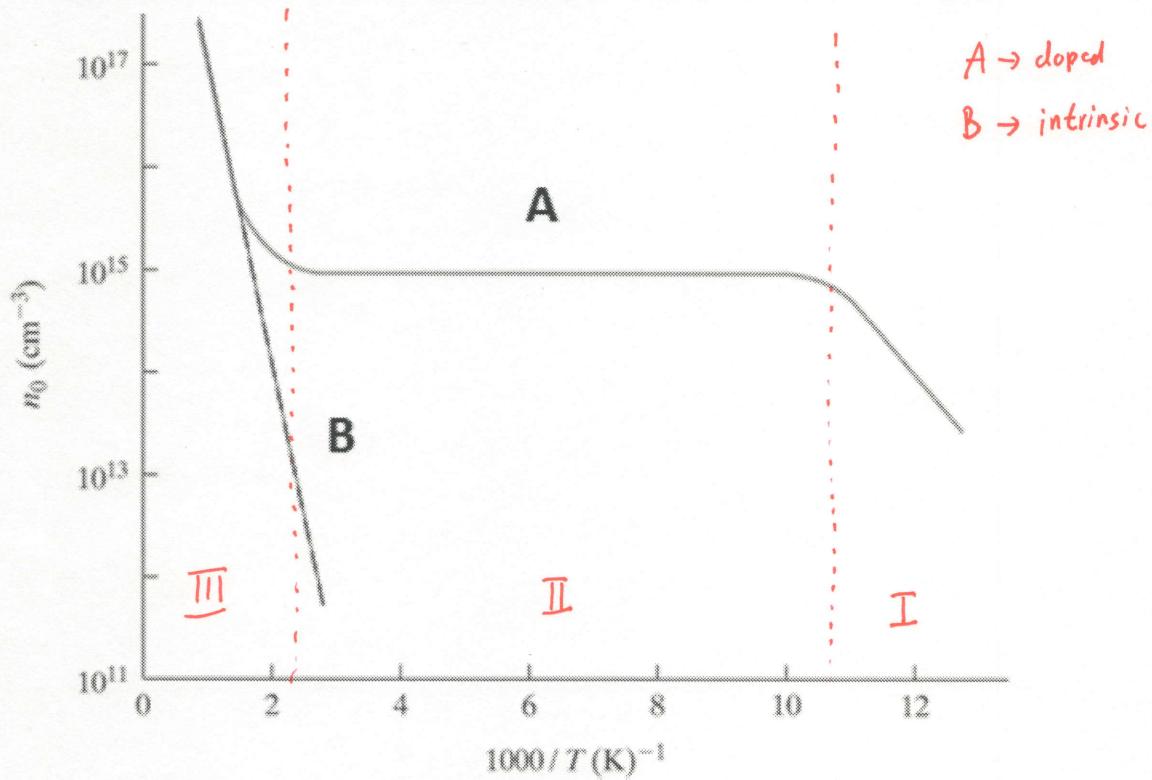
$T = 500\text{K}$ :  $n_i > N_A$  so  $E_F - E_i \ll \frac{E_g}{2}$ , or  $E_F \approx E_i$

## Problem 2: Carrier Concentration and Space Charge Neutrality

- a) What is the probability of an energy state at the Fermi level to be occupied by an electron at temperature  $T=0\text{K}$ ? How about at  $300\text{K}$ ? (2 pts)

The Fermi level is defined as the energy level where the probability of electron occupancy is  $\frac{1}{2}$  ( $f(E_F) = \frac{1}{2}$ ). This is true for all temperatures.

- b) The figure below shows the temperature dependence of the carrier concentration for two silicon samples, "A" and "B." One of the samples is intrinsic, and the other sample is doped. Please identify which sample is intrinsic and which one is doped. (3 pts) Explain the behavior of sample "A." (5 pts)



**Region I (low temperatures):**

At low  $T$ , donor states are only partially ionized, leading to a slow increase in  $n_0$  with increasing  $T$ . Very little thermal generation is present.

**Region II (medium temperatures):**

All of the donor states are fully ionized, contributing to an electron concentration of  $n_0 = N_D$ . Since  $N_D \gg n_i$  in this temperature range, the electron concentration behaves temperature-independent.

**Region III (high temperatures):**

Thermally generated carriers dominate over the donated electrons ( $n_i > N_D$ ) and the sample resembles an intrinsic semiconductor.

$$N_D = 3 \times 10^{13}$$

$$N_A = 1 \times 10^{13}$$

A silicon wafer is doped with  $3 \times 10^{13} \text{ cm}^{-3}$  phosphorus and  $1 \times 10^{13} \text{ cm}^{-3}$  boron. Assume the doping is uniform in the wafer and all the impurities are ionized.

	III A	IV A	V A	V I A
IIB	B 13	C 14	N 15	O 16
	Al	Si	P	S
	Zn 30	Ga 31	Ge 32	As 33
	Cd 48	In 49	Sn 50	Sb 51
				Te 52

c) At 300K, the intrinsic carrier concentration of silicon is approximately  $1 \times 10^{10} \text{ cm}^{-3}$ . Is this sample n type or p type? What is the majority carrier concentration? Show your work. (4 pts)

$$N_D > N_A \rightarrow \boxed{\text{n-type}}$$

$$N_D - N_A = 2 \times 10^{13} \gg n_i$$

$$n \approx N_D - N_A = \boxed{2 \times 10^{13} \text{ cm}^{-3}}$$

d) At 410K, the intrinsic carrier concentration of silicon is approximately  $1 \times 10^{13} \text{ cm}^{-3}$ . Is this sample n type or p type? Is the majority carrier concentration the same, larger, or smaller than the value calculated in c) above? Explain. (6 pts)

Since  $n_i$  is now on the same order of magnitude as  $N_D$  and  $N_A$ , we need to solve the quadratic equation:

$$n + N_A^- = p + N_D^+ \leftarrow \text{charge neutrality}$$

$$p = \frac{n_i^2}{n} \leftarrow \text{mass action law}$$

$$n + N_A^- = \frac{n_i^2}{n} + N_D^+$$

$$n^2 + (N_A^- - N_D^+) n - n_i^2 = 0$$

$$n = \frac{-(N_A^- - N_D^+) \pm \sqrt{(N_A^- - N_D^+)^2 + 4n_i^2}}{2}$$

$$= \frac{2 \times 10^{13} \pm \sqrt{(2 \times 10^{13})^2 + 4(10^{13})^2}}{2} \leftarrow \text{negative root leads to negative (nonphysical) carrier concentration}$$

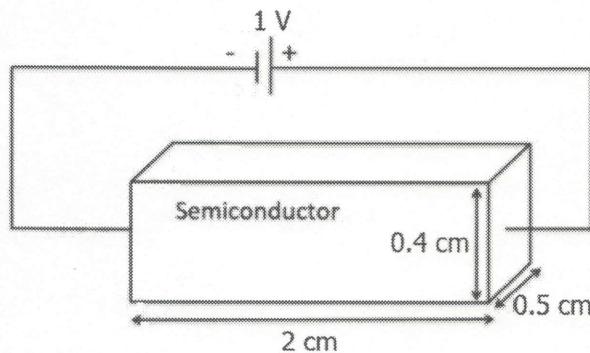
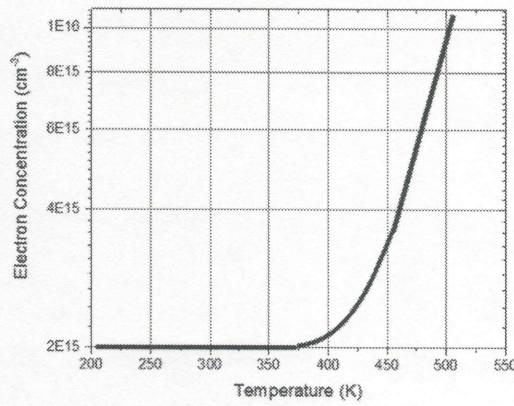
$$= \boxed{(1 + \sqrt{2}) \times 10^{13} \text{ cm}^{-3}}$$

Since  $N_D > N_A$ , the sample is still **n-type**.

Since there are more EHPs generated at higher T, both the majority & minority carrier concentrations have to be **larger**

### Problem 3: Drift and Resistance

The temperature dependence of the electron concentration in a semiconductor that is doped only with donors is shown below. A bias voltage is applied to a bar of this material as shown below. The electron and hole mobilities at 300K are 5000 and 3000 cm<sup>2</sup>/V-sec, respectively. The electron and hole mobilities at 500K are 3000 and 2500 cm<sup>2</sup>/V-sec, respectively. At 300K, assume complete donor ionization and an intrinsic carrier concentration of 10<sup>10</sup> /cm<sup>3</sup>.



- a) Why do both the electron and hole mobility decrease at high temperatures (~500K) relative to room temperature (~300K)? Explain briefly. (4 pts)

The reason the mobility decreases for both types of carriers is based on the notion of an increase in scattering events. As temperature increases, the lattice vibrations (atomic vibrations) increase, thereby increasing the likelihood of collisions between charged carriers, scattering off, and further affecting lattice vibrations. As scattering events increase, the mobility reduces for a free carrier.

- b) Find the current flowing through the sample at 300K. (6 pts)

$$J = \sigma \vec{E} = q(n \cdot \mu_n + p \cdot \mu_p) \left( \frac{\text{Volts}}{\text{length}} \right)$$

$$= 1.6 \cdot 10^{-19} \left( 2 \cdot 10^{15} \frac{\text{cm}^3}{\text{s} \cdot \text{V}} \cdot 5000 \frac{\text{cm}^2}{\text{V} \cdot \text{s}} + \frac{(1.5 \cdot 10^{10})^2}{2 \cdot 10^{15} \frac{\text{cm}^3}{\text{s} \cdot \text{V}}} \cdot 3000 \frac{\text{cm}^2}{\text{V} \cdot \text{s}} \right) \left( \frac{1 \text{ Volt}}{2 \text{ cm}} \right)$$

since  $n \gg p$ , we can neglect the  $p \cdot \mu_p$  contribution. We also must make sure we match units.

$$= 1.6 \cdot 10^{-19} \left( 1 \cdot 10^{19} \frac{\text{cm}^{-1} \text{V}^{-1} \text{s}^{-1}}{\text{s} \cdot \text{cm}^2} \right) (0.5 \text{ V} \cdot \text{cm}^{-1}) = (1.6)(.5) \text{ C} \cdot \text{s}^{-1} \text{ cm}^{-2}$$

$$I = J \cdot \text{Area} = \left( 0.8 \frac{\text{Coulombs}}{\text{s} \cdot \text{cm}^2} \right) (0.4 \text{ cm} \cdot 0.5 \text{ cm})$$

$$= 0.16 \text{ Amps}$$

- c) At 500K does the ratio of hole current to electron current increase, decrease, or stay the same? Explain. (6 pts)

At room temperature (300 K), we see that the electron contribution is much larger than holes, yet as we raise temperature to 500K this changes. At lower temperatures, the electron carrier concentration dominates due to the n-type donor doping; at elevated temperatures, the thermalization increases  $n$ ; and thus increases more electron-hole pairs (EHP's) so much so that thermalized carriers dominate doping. Since thermalization creates both electrons and holes equally, the minority carriers (holes) will feel a larger increase as  $p \rightarrow n$ , so the ratio increases. To confirm that mobility doesn't offset this, we check:

$\frac{J_p}{J_n} \propto \frac{p\mu_p}{n\mu_n}$ . Between 300K and 500K, the relative change in mobility ratios changes but concentration changes more and dominates.

- d) What will happen to the value of the electron current when we lower the temperature from 300K to 250K? Circle one and explain briefly. (4 pts)

INCREASE

DECREASE

STAY THE SAME

NOT ENOUGH INFORMATION

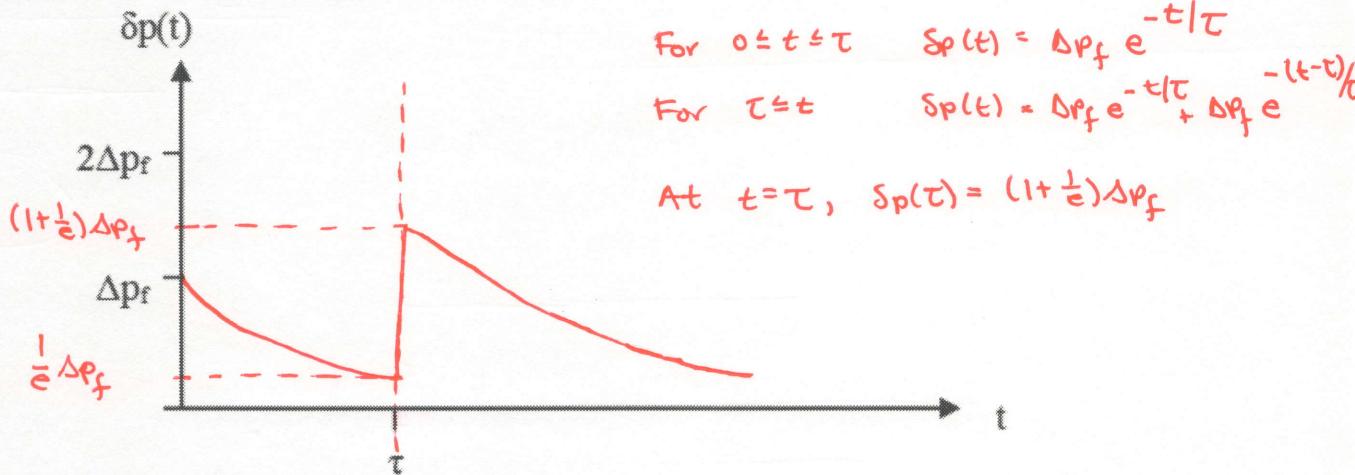
Based on the graph, we can expect  $n$  to stay relatively constant between 250K and 300K, yet since  $I_n \propto n\mu_n$  we must also consider changes in mobility for electrons. Around the temperature change 300K  $\rightarrow$  250K, we would expect  $\mu_n$  to increase as you drop in temperature due to a reduction in scattering events.

However, it can also be argued that since the material used is not given, it is not known for sure where the crossover from increasing  $\mu_n$  to decreasing  $\mu_n$  per temperature is, so not enough information is known to determine whether this change increases or decreases current. This is also acceptable if explained fully.

### Problem 4: Excess Carriers with Generation and Recombination

An n-type Si sample with  $N_D = 10^{15} \text{ cm}^{-3}$  and maintained at room temperature is illuminated by **two flashes of light** from a stroboscope. Each flash creates  $\Delta p_f = 10^{12} \text{ cm}^{-3}$  excess holes **uniformly** throughout the Si sample. The first flash occurs at  $t = 0$  and the second occurs at  $t = \tau$ , where  $\tau$  is the minority carrier lifetime in the sample. The flashes of light themselves are of infinitesimally short duration compared to  $\tau$ . For this sample answer the following questions. You may use:  $\ln 10^5 = 11.5$ ,  $\ln 100 = 4.61$ ,  $\ln 1.5 = 0.405$ ,  $e = 2.72$ ,  $e^{-1} = 0.368$ ,  $n_i = 1.5 \times 10^{10} \text{ cm}^{-3}$ ,  $E_g$  for Si = 1.12 eV

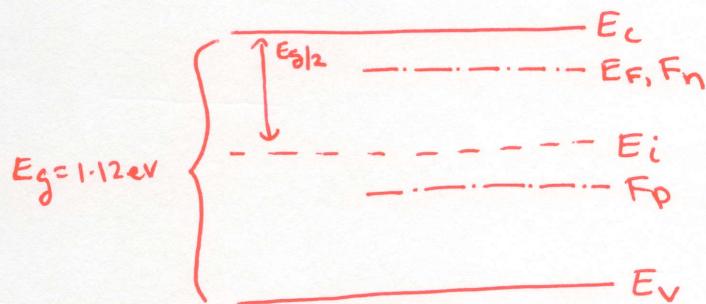
- a) Sketch on the linear scale shown below (based on qualitative reasoning), the expected general variation of  $\delta p(t)$  as a function of time,  $t$ . Explain. (8 pts)



- b) Do low-level injection conditions prevail at all times inside the Si sample? Explain. (5 pts)

- $\delta p(t)|_{\max} = \delta p(t=\tau) = (1 + \frac{1}{e})\Delta p_f = (1 + \frac{1}{e}) \times 10^{12}$
- Since  $N_D \gg n_i$ ,  $n_0 \approx N_D = 10^{15}$
- Since  $\delta p(t)_{\max} \ll n_0 \quad \forall t$ , **Low-level injection prevails at all times**

- c) Draw the energy band diagram that is applicable to this sample immediately after the first flash, at  $t=0^+$ . Show, **qualitatively**, the values of  $F_n$  and  $F_p$ . Also **qualitatively** show  $E_c$ ,  $E_i$ ,  $E_F$  for equilibrium, and  $E_v$  on the diagram. (7 pts)



$$n = n_0 + \Delta n \approx n_0 \Rightarrow E_F \approx F_N$$

$$P = P_0 + \Delta p \approx \Delta p = n_i e^{(E_i - F_p)/kT}$$

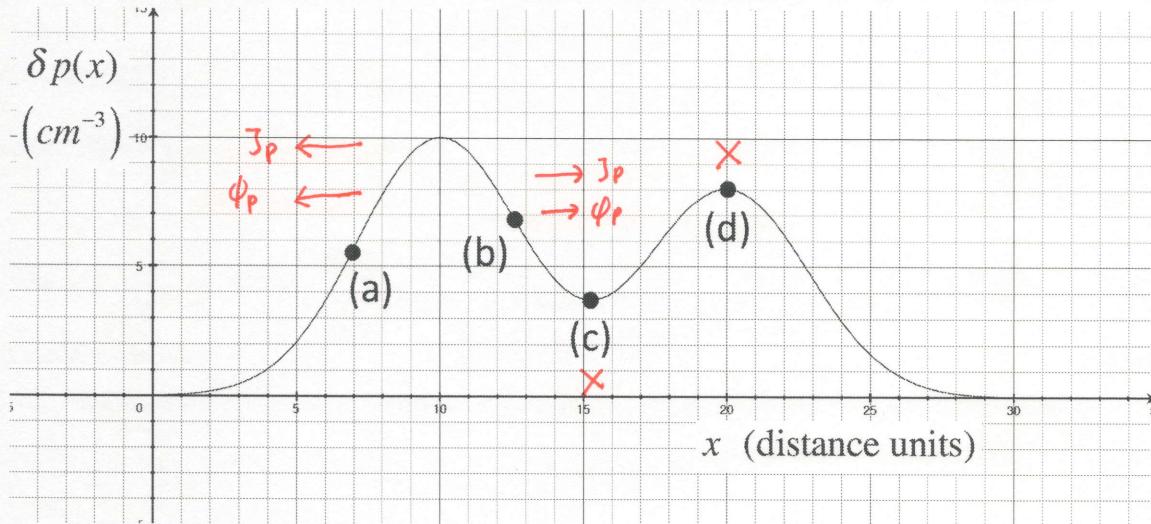
$$E_i - F_p = kT \ln \frac{10^{12}}{1.5 \times 10^{10}} \approx 0.108 \text{ eV}$$

$$E_F - E_i = kT \ln \frac{10^{15}}{1.5 \times 10^{10}} \approx 0.290 \text{ eV}$$

**(\*) Numerical answers not required for full credit.**

### Problem 5: Diffusion

Following a perturbing event, a semiconductor bar has the following excess carrier distribution:



Please answer the following questions regarding the diffusion of the excess holes  $\delta p(x)$ :

- a) At points (a), (b), (c), and (d) draw arrows to indicate the direction of hole flow  $\Phi_p(x)$  and current density  $J_p(x)$ , or an "X" if the magnitude is 0. Clearly label the arrows to differentiate direction of flow from direction of current. (8 pts)
- b) The distribution above is a sum of Gaussians and can be described by the equation:

$$\delta p(x) = Ae^{\left(\frac{-(x-a)^2}{c}\right)} + (0.8 \times A)e^{\left(\frac{-(x-b)^2}{c}\right)}$$

Write the expression for the current density  $J_p(x)$  given no applied electric field. (12 pts)

$$\begin{aligned}
 J_p(x) &= -q D_p \frac{d p(x)}{dx} \\
 &= -q D_p \frac{d}{dx} \left( A e^{-\frac{(x-a)^2}{c}} + 0.8 A e^{-\frac{(x-b)^2}{c}} \right) \\
 &= -q D_p A \left( -\frac{2(x-a)}{c} e^{-\frac{(x-a)^2}{c}} + 0.8 \left( -\frac{2(x-b)}{c} \right) e^{-\frac{(x-b)^2}{c}} \right) \\
 &= \frac{2q D_p A}{c} \left( (x-a) e^{-\frac{(x-a)^2}{c}} + 0.8 (x-b) e^{-\frac{(x-b)^2}{c}} \right)
 \end{aligned}$$